



Product Change Notification: CAAN-10UJOE243

Date:

16-Jun-2026

Product Category:

Ethernet Bridges

Notification Subject:

CCB 8340 Final Notice: Qualification of MTAI as an additional assembly site for LAN7430/Y9X, LAN7430-I/Y9X, LAN7430T/Y9X and LAN7430T-I/Y9X catalog part numbers (CPN) available in 48L VQFN (7x7x1.0mm) package.

Affected CPNs:

[CAAN-10UJOE243_Affected_CPN_06162026.pdf](#)

[CAAN-10UJOE243_Affected_CPN_06162026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MTAI as an additional assembly site for LAN7430/Y9X, LAN7430-I/Y9X, LAN7430T/Y9X and LAN7430T-I/Y9X catalog part numbers (CPN) available in 48L VQFN (7x7x1.0mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change		Change (Yes/No)
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	Microchip Technology Thailand (HQ)	Yes

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 16, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CAAN-10UJOE243_Pre and Post_Change_Summary.pdf

PCN_CAAN-10UJOE243_Qualification Report.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN):

LAN7430/Y9X

LAN7430-I/Y9X

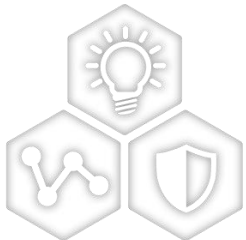
LAN7430T/Y9X

LAN7430T-I/Y9X

CCB 8340
Pre and Post Change Summary
PCN #: CAAN-10UJOE243

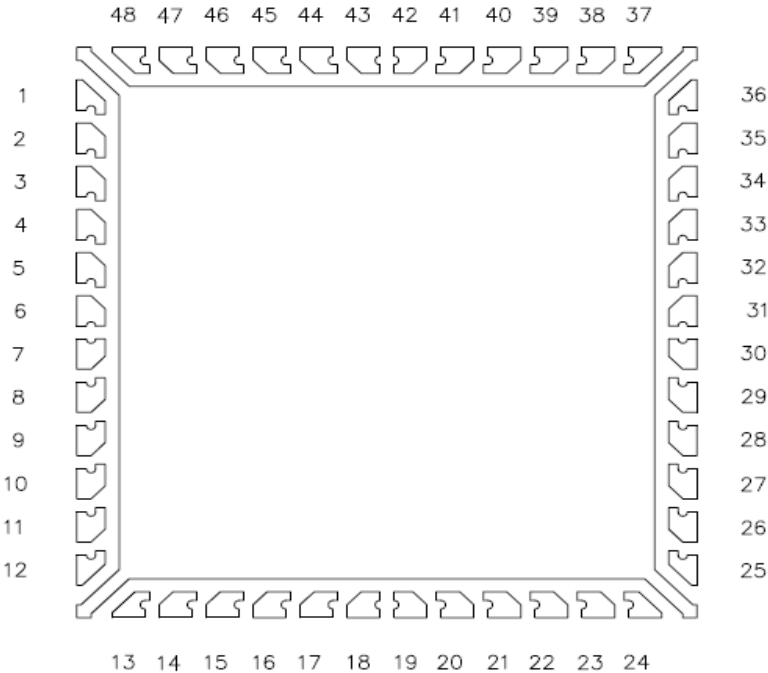
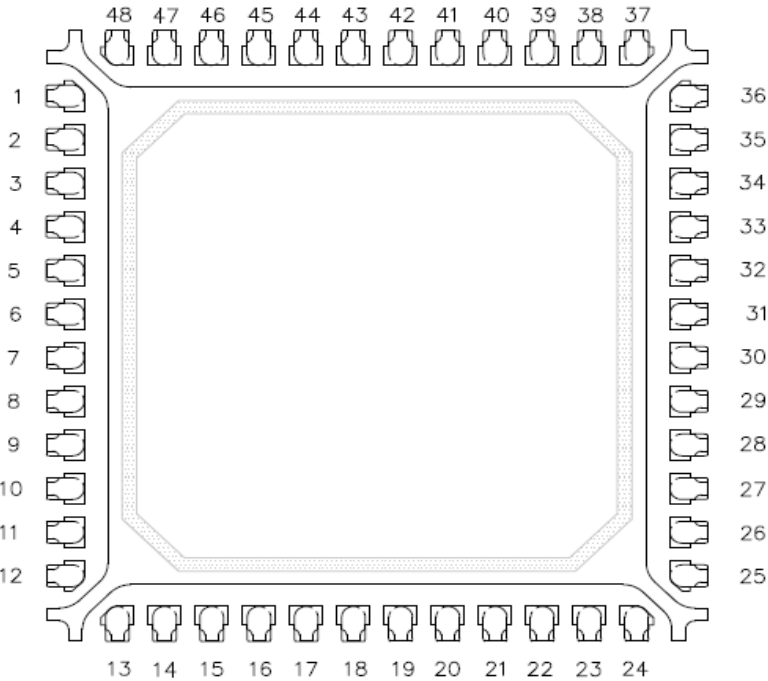


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LEAD FRAME COMPARISON

ASE		MTAI	
			
Lead frame Material	C194	Lead frame Material	C194

Note: Not to scale



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QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN#: CAAN-10UJOE243

Date:
June 16, 2026

Qualification of MTAI as an additional assembly site for LAN7430/Y9X, LAN7430-I/Y9X, LAN7430T/Y9X and LAN7430T-I/Y9X catalog part numbers (CPN) available in 48L VQFN (7x7x1.0mm) package. This is a Q006 grade 3 qualification and qualification by similarity (QBS).



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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MTAI as an additional assembly site for LAN7430/Y9X, LAN7430-I/Y9X, LAN7430T/Y9X and LAN7430T-I/Y9X catalog part numbers (CPN) available in 48L VQFN (7x7x1.0mm) package. This is a Q006 grade 3 qualification and qualification by similarity (QBS).
CN	ES353881
QUAL ID	R2100291 Rev. A
MP CODE	STB037Y9XAB1
Part No.	LAN7800-I/Y9X
Bonding No.	BDM-002844 Rev. A
CCB No.	4572 (Qual Date: 05/20/21) and 8340
<u>Package</u>	
Type	48L VQFN
Package size	7 x 7 x 1.0 mm
<u>Lead Frame</u>	
Paddle size	224 x 224 mils
Material	C194
Surface	Ag ring plated on DAP
Process	Etched
Lead Lock	No
Part Number	10104817
<u>Material</u>	
Epoxy	3280
Wire	CuPdAu wire
Mold Compound	G700LTD
Plating Composition	Matte Sn



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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI215003167.000	TC14920515342.110	2111GM4
MTAI215003169.000	TC14920515342.110	2111GUQ
MTAI215003170.000	TC14920515342.110	2111GUR

Result

☒ Pass ☐ Fail ☐ _____

48L VQFN (7x7x1.0 mm) assembled by MTAI pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C
reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 3)	30°C/ 60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020E)	IPC/JEDEC C J-STD- 020E	135	0/135	Pass	
<u>Precondition Prior Perform Reliability Tests</u> (At MSL Level 3)	Electrical Test: +25°C and 85°C System: LTX_D1X Bake 150°C, 24 hrs System: CHINEE 30°C/60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 Electrical Test: +25°C and 85°C System: LTX_D1X	JESD22- A113	693(0)	693 693 693 693 0/693	 Pass	Good Devices

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +125°C, 1000 Cycles System: TABAI ESPEC TSA-70H Electrical Test: +85°C System: LTX_D1X	JESD22-A104		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>10.00 grams)		45 (0)	0/45	Pass	
	Stress Condition: -55°C to +125°C, 2000 Cycles System: TABAI ESPEC TSA-70H Electrical Test: +85°C System: LTX_D1X		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>10.00 grams)		45 (0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: 1.2 Volts, 2.5 Volts, 3.3 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C and 85°C System: LTX_D1X		231(0)	0/231	Pass	77 units / lot
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>10.00 grams)		45 (0)	0/45	Pass	
	Stress Condition: +130°C/85%RH, 192 hrs. Bias Volt: 1.2 Volts, 2.5 Volts, 3.3 Volts System: HAST 6000X			231		
	Electrical Test: +25°C and 85°C System: LTX_D1X		231(0)	0 /66	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>10.00 grams)		45 (0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: LTX_D1X		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 150°C, 500 hrs System: TPS DC-166-F-ST350	JESD22-A103		135		45 units / lot
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	
	Stress Condition: Bake 150°C, 1000 hrs System: TPS DC-166-F-ST350			135		
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	
Solderability Temp 215°C	Steam Aging: Temp 93°C,8Hrs System: SAS-3000 Solder Dipping: Solder Temp.215°C Solder material: SnPb Sn63, Pb37 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22 (0)	22 22 0/22	Pass	
Solderability Temp 245°C	Steam Aging: Temp 93°C,8Hrs System: SAS-3000 Solder Dipping:Solder Temp.245°C Solder material:Pb Free Sn 95.5Ag3.9 Cu0.6 System: ERSA RA 2200D Visual Inspection: External Visual Inspection	J-STD-002	22 (0)	22 22 0/22	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Physical Dimensions	Physical Dimension, 10 units / lot from 3 lot	JESD22- B100/B108	30(0) Units	0/30	Pass	
Bond Strength Data Assembly	Wire Pull (>3.00 grams)	M2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>10.00 grams)	JESD22- B116	30 (0) bonds	0/30	Pass	



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PACKAGE QUALIFICATION REPORT

Purpose	Qualification of MTAI as an additional assembly site for LAN7430/Y9X, LAN7430-I/Y9X, LAN7430T/Y9X and LAN7430T-I/Y9X catalog part numbers (CPN) available in 48L VQFN (7x7x1.0mm) package. This is a Q006 grade 3 qualification and qualification by similarity (QBS).
CN	E000246496
QUAL ID	R2401317 Rev. A
MP CODE	STB071KDXC50
Part No.	USX5007C/KD
Bonding No.	BD-002245 Rev. 01
CCB No.	6910 (Qual Date: 03/04/25) and 8340
<u>Package</u>	
Type	100L VQFN
Package size	12 x 12 x 0.9mm
<u>Lead Frame</u>	
Paddle size	323 x 323mils
Material	EFTEC64
Surface	Ag signal ring plated on DAP
Process	Etched
Lead Lock	No
Part Number	10110011
Treatment	Roughening
<u>Material</u>	
Epoxy	QMI519
Wire	CuPdAu wire
Mold Compound	G700LTD
Plating Composition	Matte Sn



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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI252600940.000	TC14924313854.200	2439YD7
MTAI252601144.000	TC14924313854.200	2439YT8
MTAI252601148.000	TC14924313854.200	2439YTK

Result

☒ Pass ☐ Fail ☐ _____

100L VQFN (12x12x0.9mm) assembled by MTAI pass reliability test per QCI-39000.
This package was qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C
reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 3)	30°C/ 60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020E)	IPC/JEDEC C J-STD- 020E	135(0)	0/135	Pass	
Precondition Prior Perform Reliability Tests (At MSL Level 3)	Electrical Test: +25°C and 85°C System: LTX_D1X Bake 150°C, 24 hrs System: CHINEE 30°C/60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 Electrical Test: +25°C and 85°C System: LTX_D1X	JESD22- A113	693(0)	0/693 693 693 693 0/693	Pass Pass	Good Devices

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -55°C to +125°C, 500 Cycles System : VOTSCH Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)	JESD22-A104		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	
			45 (0)	0/45	Pass	
	Stress Condition: -55°C to +125°C, 1000 Cycles System: VOTSCH Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)			231		
			231(0)	0/231	Pass	
			45 (0)	0/45		

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	Stress Condition: +110°C/85%RH, 264 hrs. Bias Volt: PS1:1.32 Volts, PS3: 3.63 Volts System: HAST 6000X Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)	JESD22-A110		231		Parts had been pre-conditioned at 260°C
			231(0)	0/231	Pass	77 units / lot
			45 (0)	0/45	Pass	
	Stress Condition: +110°C/85%RH, 528 hrs. Bias Volt: PS1:1.32 Volts, PS3:3.63 Volts System: HAST 6000X Electrical Test: +25°C and 85°C System: LTX_D1X Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)	JESD22-A110		231		
			231(0)	0/231	Pass	
			45 (0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED-HAST	Stress Condition: +110°C/85%RH, 264 hrs. System: HAST 6000X	JESD22- A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: LTX_D1X		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	Stress Condition: Bake 150°C, 500 hrs System: CHINEE	JESD22- A103		135		45 units / lot
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	
	Stress Condition: Bake 150°C, 1000 hrs System: CHINEE			135		
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Cross section	Cross section Inspection 5 units / lot		15(0) Wires	0/15	Pass	
Bond Strength	Wire Pull (> 3.00 grams)	Mil. Std. 883-2011	30 (0) Wires	0/30	Pass	
Data Assembly	Bond Shear (>8.00 grams)	CDF-AEC- Q100-001	30 (0) Bonds	0/30	Pass	